

曜凌光電股份有限公司

 住址: 42878 台中市大雅区科雅路 25 號 5F
 WEB: <u>http://www.Raystar-Optronics.com</u>

 5F., No.25, Keya Rd., Daya Dist., Taichung
 E-mail: sales@raystar-optronics.com

 City 428, Taiwan
 Tel:886-4-2565-0761

RG160160B-YHY-X

SPECIFICATION

CUSTOMER:

APPROVED BY

PCB VERSION

DATE

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

ISSUED DATE:



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1. Revision History

DATE	VERSION	REVISED PAGE NO.	Note
2010/03/17 2012/09/20	1 2	29	First issue Add Recommendable storage



2. General Specification

The Features of the Module is description as follow:

- Module dimension: 85.0 x 100.0 x 14.5(max.) mm3
- View area: 62.0 x 62.0 mm2
- Active area: 60.76 x 60.76 mm2
- Number of Dots: 160 x 160
- Dot size: 0.34 x 0.34 mm2
- Dot pitch: 0.38 x 0.38 mm2
- LCD type: STN Positive, Yellow Green Transflective
- Duty: 1/160
- View direction: 6 o'clock
- Backlight Type: LED, Yellow Green



3. Module Coding System

R	G	160160	В	-	Y	н	Y	-	X
1	2	3	4	-	5	6	7	-	8

Item		Description	on							
1	R : Raystar C	optronics Inc.								
2	Dianlay	C: Character Type,	\sim							
2	Display	G : Graphic Type								
3	Number of dot	ts:160x160 Dots								
4	Serials code	-	100000 march V							
		P : TN Positive, Gray								
		N : TN Negative,								
		G : STN Positive, Gray								
5	LCD	Y: STN Positive, Yellow G	Green							
		B : STN Negative, Blue 🧹								
		F : FSTN Positive								
		T : FSTN Negative	, , , , , , , , , , , , , , , , , , ,							
		A : Reflective, N.T, 6:00	K : Transflective, W.T,12:00							
	Polarizer Type.	D: Reflective, N.T, 12:00	1 : Transflective, U.T,6:00							
		G: Reflective, W. T, 6:00	4 : Transflective, U.T.12:00							
		J: Reflective, W. T, 12:00	C: Transmissive, N.T,6:00							
6	Temperature	0 : Reflective, U. T, 6:00	F: Transmissive, N.T,12:00							
	range,	3 : Reflective, U. T, 12:00	I: Transmissive, W. T, 6:00							
	View	B: Transflective, N.T,6:00	L: Transmissive, W.T,12:00							
	direction	E: Transflective, N.T.12:00	2 : Transmissive, U. T, 6:00							
		H:Transflective, W.T,6:00	5 : Transmissive, U.T,12:00							
		N : Without backlight	Y : LED, Yellow Green							
2	X X	P: EL, Blue green	A : LED, Amber							
7	Backlight	T : EL, Green	W : LED, White							
\bigcirc		D : EL, White	O:LED, Orange							
		F : CCFL, White	B : LED, Blue							
8	Special code	X: Without Negative Voltage	<u>,</u>							



4. Interface Pin Function

Pin No.	Symbol	Level	Description
1	FGND		Frame Ground
2	V _{SS}		Power supply (0V)
3	Vdd		Power supply (+5V)
4	Vo		Contrast Adjustment
5	R/W	H/L	H : read , L : write
6	E	H/L	Enable Signal
7	CS	L	Chip enable active " L "
8	RS	H/L	H : Instruction , L : Data
9	NC		No Connection
10	/RST	L "A	Reset active " L "
11	DB0	H/L	Data bus line
12	DB1	HIL	Data bus line
13	DB2	H/L	Data bus line
14	DB3	H/L	Data bus line
15	DB4	H/L	Data bus line
16	DB5	H/L	Data bus line
17	DB6	H/L	Data bus line
18	DB7	H/L	Data bus line
19	NC		No Connection
20	NC		No Connection



5. Outline Dimension & Block Diagram





6. Display Control Instruction

The LCM has built-in a LC7981 LSI Controller, it stores display data sent from the 8 bit microcomputer in the display RAM attached externally and generates dot matrix LC drive signal.

The LC7981 has two modes-the graphic mode, in which each bit of data from the external RAM either lights or doesn't light a dot in the LCD, and the character mode in which character codes stored in the external RAM generate dot patterns through the built-in character-generator ROM (CGROM)

below is its block diagram

Description of each block

• Register

The LC7981 has 5 types of registers-the instruction register, data input register, data output register, dot register, and mode control register.

The instruction register stores such instruction codes as the start address, cursor address specification, etc. It consists of 4 bits, and the lower 4 bits of the data bus, DB0 to DB3, are written into it.

The data input register temporarily stores data to be written into the external RAM, dot register, and mode control register. It consists of 8 bits.

The data output register temporarily stores data to be read from external RAM, and consists of 8 bits. What the cursor address is written into the cursor address counter via the data input register and the memory read instruction is set in the instruction register, data in external RAM is read into the data output register by internal operation. With the next instruction, the MPU reads the data output register, and completes data transfer to the MPU.

The dot register stores dot information such as the character pitch, the number of vertical dots, etc. Data sent from the MPU is written into the dot register via the data input register.

The mode control register stores LCD status information such as display on/off and cursor on/off/blink. It consists of 6 bits. Data sent from the MPU is written into this register via the data input register.

• Busy flag

When the Busy flag is "1", the LC7981 is operating internally. At this time, the next instruction cannot be accepted. The Busy flag is output to DB7 when RS=1, RW=1. The next instruction must be written after ensuring that the Busy flag is "0". When the maximum value of the read cycle time or write cycle time has been passed after the execution of the preceding data read instruction or data write instruction, the next instruction can be executed without checking the Busy flag.

Character generator ROM



The character generator ROM has a total of 7360 bits and stores data on 192 kinds of characters. Character codes from the external RAM and row codes from the row address counter are added to address signals, and ROM outputs 5-bit dot data.

There are 192 kinds of character fonts, of which 160 are 5×7 and 32 are 5×11. With extended ROM. character fonts can be increased to 256 kinds sized 8×16.

Cursor address counter

The cursor address counter is a 16-bit counter which can be preset by instruction.. When data is read from or written into external RAM (i. e., read/write of display dot data or character codes), the counter retains the addresses. The value indicated on the cursor address counter is automatically incremented by 1 when instructions to read/write display data and to perform bit set/clear are issued.

Cursor signal generator

In the character mode, the cursor can be displayed by means of instructions. The cursor is generated automatically when the cursor address counter and the row address counter reach the specified value.

Display control instruction

Display is controlled by writing data into the instruction register and 13 data registers. The instruction register and the data register are distinguished by the RS signal. First, write 4-bit data in the instruction register when RS=1, then specify the code of the data register. Next, with RS=0, write 8-bit data in the data register, which executes the specified instruction.

A new instruction cannot be accepted while an old instruction is being executed. As the Busy flag is set under this condition, write an instruction only after reading the Busy flag and making sure that it is 0.

However, the next instruction can be executed without checking the Busy flag when the maximum read cycle time or the write cycle time has been exceeded after execution of the previous data read instruction or the data write instruction. The Busy flag does not change when data is written into the instruction register (RS=1). Therefore, the Busy flag need not be checked immediately after writing data into the instruction register.



1)Mode control

Write code "00H" (in hexadecimal notation) in the instruction register and specify the mode control register.

Register		R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	
Instructio	on Reg.	0	1	0	0	0	0	0	0	0	0	À
Mode	control	0	0	0	0			and the second				
Reg.										A		

DB5	DB4	DB3	DB2	DB1	DB0-	Cursor/blink	CG	Graphic/character display
		0	0			Cursor OFF		
		0	1			Cursor ON	Ö (
		1	0		0	Cursor OFF character blink	suilt-in	d.
		1	1	0		Cursor blink	Щ	Character display
1/0	1/0	0	0	0		Cursor OFF	Ċ	Character display
		0	1		1	Cursor ON	Ŭ	
		1	0			Cursor OFF	ina	
		-	0			character blink	xte	
		1	1	100	(California)	Cursor blink	ш	
		0	0	<u>↑</u>	0		\succ	Graphic mode
Display ON/OFF	Master/slave	Blink	Cursor	Mode	External/ Built in CG			





2)Setting the character pitch

Register	R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Instruction Reg.	0	1	0	0	0	0	0	0	0	1
Character pitch Reg.	0	0	(Vp-1) Binary 0				(Hp	-1) Bir	ary	

Vp is the number of vertical dots per character. Determine Vp with the pitch between two vertically placed characters taken into consideration. This value is meaningful only in the character display mode: It is invalid in the graphic mode.

In character mode. Hp indicates the number of horizontal dots per character, from the leftmost part of one character to the leftmost part of the next. In the graphic mode, Hp indicates how many bits (or dots) from RAM appear in a 1-byte display.

Hp must take one of the following three values.

Нр	DB2	DB1	DB0	
6	1	0	1	Horizontal character pitch 6
7	1	1	0	Horizontal character pitch 7
8	1	1	1	Horizontal character pitch 8

R/W RS DB7 DB6 Register DB5 DB4 DB3 DB2 DB1 DB0 0 0 0 0 0 0 0 1 0 Instruction Reg. 1 0 0 (H_N-1) Binary Character number Reg.

3)Setting the number of characters

in the character display mode, H_N indicates the number of characters in the horizontal direction. In the graphic mode, it indicates the number of bytes in the horizontal direction. The total number of dots positioned horizontally on the screen n is given by the formula

n= Hp×H_N

Even numbers in the range 2 to 256 (decimal) can be set as H_N .



4)Setting the time division number (display duty)

Register		R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Instruction Reg.		0	1	0	0	0	0	0	0	1	1
Time	division	0	0	(Nx-1) Binary							
Reg.											

Consequently, 1/Nx is the display duty.

Decimal numbers with the range 1 to 256 can be set as Nx. please set Nx=160

5)Setting the cursor position

									950. -	*SIET/Dec/C
Register	R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Instruction Reg.	0	1	0	0	0	0	0	1	0	0
Cursor position Reg.	0	0	0	0	0	0	0 (Cp-1) Binary			

In the character display mode, Cp indicates the line at which the cursor is displayed. For example, when Cp=8 (decimal) is specified, the cursor is displayed beneath the character of the 5×7 dot-font. The horizontal length of the cursor equals Hp (the horizontal character pitch). Decimal values in the range 1 to 16 can be assigned to Cp. When the value is less than the vertical character pitch Vp(Cp \leq Vp), display priority is given to the cursor (provided the cursor display is ON). The cursor is not displayed when CP> Vp. The horizontal length of the cursor equals Hp.

6)Setting the display start lower address

Degister		DC					200	200		
Register	R/W	RO		DBO	DBD	DB4	DB3	DBZ	DBT	DBO
Instruction Reg.	0		0	0	0	0	1	0	0	0
And		×.								
Display start	- Aler									
address Reg.	Ó	0		(sta	art add	ress lo	wer by	rte) bin	ary	
(lower byte)										

7)Setting the display start upper address

Register		R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Instruction Re	eg.	0	1	0	0	0	0	1	0	0	1
Display	start										
address	Reg.	0	0	(start address upper byte) binary							
(upper byte)											



This instruction writes the display start value in the display start address register. The display start address inn the RAM address at which data to be displayed at the leftmost position of the top line of the screen is stored. The start address consists of 16 bits (upper and lower).

8)Setting the cursor (lower) address (RAM read/write lower address)

Register	R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	~
Instruction Reg.	0	1	0	0	0	0	1	0	1	0	
Cursor address counter (lower byte)	0	0		(cur	sor ade	dress I	ower b	yte) bi	nary		and trad

9)Setting the cursor (upper) address (RAM read/write upper address)

Register	R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Instruction Reg.	0	1	0	0	0	0	1	0	1	1
Cursor address counter (upper	0	0	(cursor address upper byte) binary							
byte)						NY.	••		2	

This instruction writes the cursor address value in the cursor address counter. The cursor address indicates the address for exchanging display data and character codes with RAM. In other words, data at the address specified by the cursor address is read from or written into RAM. In character display, the cursor is displayed at the position specified by the cursor address.

The cursor address is divided into a lower address (8 bits) and an upper address (8 bits). It should be set in accordance with the following rules.

1	To rewrite (set) both lower and upper addresses.	First set the lower address, then the upper.
2	To rewrite the lower address:	Always reset the upper address after setting the lower address.
3	To rewrite the upper address only:	Set the upper address. It is necessary to reset the lower address.

The cursor address counter is a 16-bit up-counter with set/reset functions: when the Nth bit goes from 1 to 0, the count of the (N+1)th bit increments by one. Accordingly, when the lower address is set so that the lower MSB (8th bit) changes from 1 to 0, the LSB (1st bit) of the upper counter must increment by one. When setting the cursor address, set the lower and upper addresses as a 2-byte continuous instruction.



10)Writing display data

Register	R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Instruction Reg.	0	1	0	0	0	0	1	1	0	0
RAM	0	0	MS	B (patt	ern da	ta, cha	racter	code)		LSB

Write code "0CH" in the instruction register. Then, write 8-bit data with RS=0, and the data is written into RAM as display data or character codes at the address specified by the cursor address counter. After writing, the count of the cursor address counter increments by 1.

11)Reading display data

Register	R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Instruction Reg.	0	1	0	0	0	0	1	1	0	1
RAM	1	0	MS	B (patt	ern da	ta, cha	racter	code)	and the second	LSB

Write "0DH" in the instruction register. Then, establish the read status with RS=0, and data in the RAM can be read. The procedure for reading data is as follows.

This instruction outputs the contents of the data output register to DB0 to 7, then transfers the RAM data indicated by the cursor address to the data output register. It then increments the cursor address by 1, which means that correct data cannot be read in the first read operation. The specified value is output in the second read operation. Accordingly, a dummy read operation must be performed once when reading data after setting the cursor address.

12)Bit clear

Register	R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Instruction Reg.	0	1	0	0	0	0	1	1	1	0
Bit clear	0	0	0	0	0	0	0	(N _B	-1) Bir	ary

13)Bit set

Register	R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Instruction Reg	0	1	0	0	0	0	1	1	1	1
Bit set	0	0	0	0	0	0	0	(N _B	-1) Bin	ary

As the bit-clear or bit-set instruction, 1 bit of a 1 byte of data in display RAM is set to 0 or 1. The bit specified by N_B is set to 0 for the bit-clear instruction and 1 for the bit-set instruction. The RAM address is specified by the cursor address, which is automatically incremented by 1 at the completion of the instruction. NB is a value in the range from 1 to 8. The LSB is indicated by N_B =1, and the MSB by N_B =8.



Symbol

14)Reading the BUSY flag

Register	R/W	RS	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
busy flag	1	1	1/0				*			

The Busy flag is output to DB7 when read mode is established with RS=1. The Busy flag is set to 1 while any of the instructions 1) through 13) is being executed. It is set to 0 at the completion of the execution, allowing the next instruction to be accepted. No other instruction can be accepted when the Busy flag is 1. Accordingly, before writing an instruction and data, it is necessary to ensure that the Busy flag is 0. However, the next instruction can be executed without checking the Busy flag when the maximum read cycle time or the write cycle time has been exceeded after execution of the previous data read instruction or the data write instruction.

The Busy flag does not change when data is written into the instruction register (RS=1). Therefore, the Busy flag need not be checked immediately after writing data into the instruction register.

Specification of the instruction register is unnecessary to read the Busy flag.

The relation between the LCD panel display and $H_{P},\,H_{N},\,Cp,\,V_{P},\,and\,N_{X}$





RG160160B-YHY-X

Η _Ρ	Horizontal character pitch	Character pitch in the horizontal direction	6 to 8 dots	
H _N	Number of characters in the horizontal direction	Number of characters (digits) per horizontal line or the number of words per line (graphic)	Even digits in the range 2 to 256	
V _P	Vertical character pitch	character pitch in the vertical direction	1 to 16 dots	
C _P	Cursor position	The line number at which the cursor is to be displayed	1 to 16 lines	
N _X	Number of lines in the vertical direction	Display duty	1 to 256 lines	Contraction of the second

Note)

When the number of vertical dots on the screen is m and that of horizontal dots is n,

 $1/m= 1/N_X$ = display duty (nx=64)

 $n = H_P \times H_N$

m/V_P= number of display lines, $C_P\!\leq\!V_P$



Display mode

LCD Panel	A B C A B C A B C A B C	Hp = B dots
RAM	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$H_{p} \xrightarrow{b7 \ b6 \ b5 \ b4 \ b3 \ b2 \ b1 \ b0}$
Display data from the MPU	Display pattern (8 Bits)	Character code (8 Bits)
Display mode	Character display	Graphic



!

Built-in Character generator

Upper 4 bit Lower	LLLL	LLLH	LLHL	LLHH	LHLL	LHLH	LHHL	LHHH	HLLL	HLLH	HLHL	HLHH	HHLL	HHLH	HHHL	нннн
4 bit																
LLLL							••					••••	-	····.	Ċ.	 •
LLLH			-					•					•			
LLHL			::								i	·				
LLHH				•	·····	:;	:	•••••						•	:	
LHLL				÷				· •			•]!	
LHLH								.								••• ••••
LHHL							••••	••					•••			• • •
LHHH			•				•	.			••••					
HLLL											•••	•	••••••		.,I'''	
HLLH						÷		••				÷			•• 1	·
HLHL			:		•									.		
HLHH				**								•			:•:	
HHLL											•			: 	: : :-	
HHLH				•••••									•*•	•• •	•	••••
HHHL						••••		•••••						•••		
нннн				•				•			::::	·	•••		·	



7. Timing Characteristics

Read cycle



	1000			(VSS =	0 V, VDD = 5 V
ltem	Symbol	Min	Тур	Мах	Unit
Address set-up time	tAS	90	_		ns
Address hold time	tAH	10	_	_	ns
Data delay time (read)	tDDR		_	140	ns
Data hold time (read)	tDHR	10	_		ns
Data set-up time (write)	tDSW	220	_		ns
Data hold time (write)	tDHW	20			ns

765Rs.

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Note : Definition of the test waveform

2.4 Measurement point 1.5 0.45

The input terminals are driven at 2.4V and 0.45V. Timming is measured at 1.5V.

)



8. Optical Characteristics

ltem	Symbol	Condition	Min	Тур	Max	Unit
View Angle	θ(V)	CR≧2	20	_	40	deg
	(H)φ	CR≧2	-30	_	30	deg
Contrast Ratio	CR		_	3	—	À
Response Time	T rise	—		200	300	ms
	T fall		_	200	300	ms

Definition of Operation Voltage (Vop)

Definition of Response Time (Tr, Tf)





9. Absolute Maximum Ratings

ltem	Symbol	Min	Тур	Мах	Unit
Operating Temperature	T _{OP}	-20		+70	°C
Storage Temperature	T _{ST}	-30		+80	°C
Input Voltage	VI	Vss		V _{DD}	V
Supply Voltage For Logic	VDD-V _{SS}	-0.3		+7	V
Supply Voltage For LCD	VDD-V0	0	<i>6</i>	15	V

10. Electrical Characteristics

ltem	Symbol	Condition	Min	🖌 Тур	Max	Unit
Supply Voltage For			4 75	5.0	5 25	V
Logic	V DD V 55		4.75	0.0	0.20	v
		Ta=-20 ℃	_	_	21.0	V
Supply Voltage For LCD	V _{DD} -V ₀	Ta=25 ℃	_	18.0	—	V
		Ta=+70° ℃	15.4	—	_	V
Input High Volt.	Ин У	—	2.2	—	V _{DD}	V
Input Low Volt.	VíL	—	0	—	0.8	V
Output High Volt	V _{он}	—	2.4	—	V_{DD}	V
Output Low Volt.	V _{OL}	_	0	_	0.4	V
Supply Current	I _{DD}	V _{DD} =5V	7.0	7.3	8.4	mA

11. Backlight Information

Specification

PARAMETER	SYMBOL	MIN	ТҮР	MAX	UNIT	TEST CONDITION
Supply Current	ILED	400	500	750	mA	V=4.2V
Supply Voltage	V	4.0	4.2	4.4	V	
Reverse Voltage	VR	—	-	10	V	-
Luminous Intensity	IV	200	240	_	CD/M ²	ILED=500mA
Wave Length	λρ	563	568	573	nm	ILED=500mA
Life Time	—	—	100000	—	Hr.	ILED=500mA
Color	Yellow Gr	een	I			

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).





12. Reliability

Content of Reliability Test (wide temperature, -20℃~70℃)

	Environmental Test		
Test Item	Content of Test	Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80℃ 200hrs	2
Low Temperature storage	Endurance test applying the high storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70℃ 200hrs	-)
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20℃ 200hrs	1
High Temperature/ Humidity Operation	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60℃,90%RH 96hrs	1,2
Thermal shock resistance	operation -20°C 25°C 70°C 30min 5min 30min 1 cycle	-20℃/70℃ 10 cycles	-
Vibration test	Endurance test applying the vibration during transportation and using.	fixed amplitude: 15mm Vibration. Frequency: 10~55Hz. One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS= 1.5kΩ CS=100pF 1 time	

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.



13. Inspection specification

NO	Item			Criterion		AQL
		1.1 Missing ver	tical, horiz	zontal segment, se	egment contrast	
		defect.	veetev de	4		
		1.2 Missing cha	racter, ac	ot of Icon.		
	Electrical	1.3 Display mai	or no disi	nlav		
01	Testing	1.5 Current consumption exceeds product specifications				
	j	1.6LCD viewing	g angle d	efect.	- p	
		1.7 Mixed produ	uct types.			and and a second second
		1.8 Contrast de	fect.			Ϋ́.
		2.1 White and k		to on diaplay <0.2	Emm no moro	
	Black or	2.1 Write and the	vhite or bl	ack spots present	Smm, no more	
02	white spots	2 2 Denselv sp	aced. No	more than two sno	ots or lines within	2.5
	on LCD	3mm				
	(display only)					
		3.1 Round type	: As follo	wing drawing		
		Φ=(x + y) /	2			
			Å			
			A			
				X		2.5
	spots white			1		
00	spots,		500m			
03	contaminatio					
	n (3.2 Line type :	As follow	ing drawing)		
	(non-display)	· ·	Length	Width	Acceptable Q	
		\sim		W/<0.02		
		- > i ⊾ +⊄-		VV≧0.02	dense	2.5
			L≤3.0	0.02 <w≤0.03< td=""><td>denee</td><td></td></w≤0.03<>	denee	
		K.	L≦2.5	$0.03 < W \le 0.05$	2	
	X			0.05 <w< td=""><td>As round type</td><td></td></w<>	As round type	
			L			
	and the second se	If bubbles are v	visible,	Size Φ	Acceptable Q	
		specifications	ok spol not	 ወ ንቦ		
04	Polarizer	easy to find, m	ust	$\Psi \ge 0.20$	dense	25
04	bubbles	check in specify	y	0.20<Φ≦0.50	3	2.5
		direction.		$0.50 < \Phi \le 1.00$	2	
				1.00<Ф	0	
				Total Q TY	3	



NO	Item	Criterion	AQL
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination	
		Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length: 6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels:	
	Chipped	$\begin{tabular}{ c c c c c c c c c c c c c c c c c c c$	0.5
06	glass	area 1/2t < z < 2t Not exceed 1/3k x < 1/8a	2.5
	0	$\bigcirc \text{ If there are 2 or more ching, x is total length of each ching.}$	
		6.1.2 Corner crack:	
		z: Chip thickness y: Chip width x: Chip length	
		$Z \le 1/2t \qquad \text{Not over viewing} \qquad x \le 1/8a$	
		$ 1/2l < 2 \ge 2l $ INOL EXCEED 1/3K X \ge 1/88	







NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	 8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong. 	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB · COB	 10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB 	 2.5 2.5 2.5 2.5 0.65 2.5 0.65 2.5 2.5 2.5
		\mathbf{Y} X * Y<=2mm ²	
11	Soldering	 11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB. 	2.5 2.5 2.5 0.65



12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.2.512.2 No cracks on interface pin (OLB) of TCP.0.65	NO	Item	Criterion	AQL
1212.3 No contamination, solder residue or solder balls on product.2.5 2.512.4 The IC on the TCP may not be damaged, circuits.2.5 2.512.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it causes the interface pin to sever.2.512General appearance12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.2.512.7 Sealant on top of the ITO circuit has not hardened.0.6512.8 Pin type must match type in specification sheet.0.6512.9 LCD pin loose or missing pins.0.6512.10 Product packaging must the same as specified on packaging specification sheet.0.6512.11 Product dimension and structure must conform to product specification sheet.0.65	12	General appearance	 12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP. 12.2 No cracks on interface pin (OLB) of TCP. 12.3 No contamination, solder residue or solder balls on product. 12.4 The IC on the TCP may not be damaged, circuits. 12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it causes the interface pin to sever. 12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color. 12.7 Sealant on top of the ITO circuit has not hardened. 12.8 Pin type must match type in specification sheet. 12.9 LCD pin loose or missing pins. 12.10 Product packaging must the same as specified on packaging specification sheet. 12.11 Product dimension and structure must conform to product specification sheet. 	2.5 0.65 2.5 2.5 2.5 2.5 2.5 2.5 0.65 0.65 0.65 0.65

14. Precautions in use of LCD Modules

- 1. Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- 2. Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- 3. Don't disassemble the LCM.
- 4. Don't operate it above the absolute maximum rating.
- 5. Don't drop, bend or twist LCM.
- 6. Soldering: only to the I/O terminals.
- 7. Storage: please storage in anti-static electricity container and clean environment.
- Raystar have the right to change the passive components (Resistors,capacitors and other passive components will have different appearance and color caused by the different supplier.)
- 9. Raystar have the right to change the PCB Rev.





15. Material List of Components for RoHs

1. RAYSTAR Optronics Co., Ltd. hereby declares that all of or part of products, including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A : The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	> 1000 ppm
Above limit	l ted value is	set up acco	ording to Re	DHS.		

- 2. Process for RoHS requirement :
 - (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
 - (2) Heat-resistance temp. :

Reflow : 250°C, 30 seconds Max.;

Connector soldering wave or hand soldering : 320° C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : $235\pm5^{\circ}$ C ;

Recommended customer's soldering temp. of connector : 280° C, 3 seconds.

16. Recommendable storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module



		Page: 1					
LCM Sample Estimate Feedback Sheet							
Module Number :							
1 <u> Panel Specification</u> :							
1. Panel Type:	Pass	□ NG ,					
2. View Direction :	Pass	□ NG ,					
3. Numbers of Dots :	Pass	□ NG ,					
4. View Area :	Pass	□ NG ,					
5. Active Area :	Pass	□ NG ,					
6.Operating	Pass	🗆 NG ,					
Temperature :							
7.Storage Temperature :	Pass	🗆 NG ,					
8.Others :							
2 <u>Mechanical Specification</u>	<u>on</u> :						
1. PCB Size :	Pass	□ NG ,					
2.Frame Size :	Pass	□ NG ,					
3.Materal of Frame :	Pass	□ NG ,					
4.Connector Position :	Pass	🗆 NG ,					
5.Fix Hole Position :	Pass	🗆 NG ,					
6.Backlight Position :	Pass	□ NG ,					
7. Thickness of PCB :	Pass	🗆 NG ,					
8. Height of Frame to	Pass	□ NG ,					
PCB :							
9.Height of Module :	🗆 Pass	□ NG ,					
10.Others :	Pass	🗆 NG ,					
3 · <u>Relative Hole Size</u> :							
1.Pitch of Connector :	Pass	□ NG ,					
2.Hole size of	Pass	□ NG ,					
Connector :	4						
3.Mounting Hole size	Pass	□ NG ,					
4.Mounting Hole Type :	Pass	□ NG ,					
5.Others	Pass	□ NG ,					
4 · <u>Backlight Specification</u>	:						
1.B/L Type	Pass	□ NG ,					
2.B/L Color :	Pass	□ NG ,					
3.B/L Driving Voltage (Reference for LED Type) : □ Pass □ NG ,							
4.B/L Driving Current :	□ Pass	□ NG ,					
5.Brightness of B/L :	□ Pass	□ NG ,					
6.B/L Solder Method :	□ Pass	□ NG ,					
7.Others :	Pass	□ NG ,					

>> Go to page 2 <<



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Page: 2

Module Number :								
5 · Electronic Characteristics of Module								
1.Input Voltage :	Pass	□ NG ,						
2.Supply Current :	Pass	□ NG ,						
3.Driving Voltage for LCD :	Pass	□ NG ,						
4.Contrast for LCD :	Pass	□ NG ,						
5.B/L Driving Method :	Pass	□ NG ,						
6.Negative Voltage	Pass	□ NG ,						
Output :								
7.Interface Function :	Pass	□ NG ,						
8.LCD Uniformity :	Pass	□ NG ,						
9.ESD test :	Pass	□ NG ,						
10.Others :		□ NG ,						
6 ∖ <u>Summary</u> :								

Sales signature : _____ Customer Signature : _____

Data	•	1	1
Date	•	1	1